



NXT-DSB

Very high environmental resistance for dual interface solutions

With Linxens NXT-DSB's thicker plating configuration, it provides further environmental resistance and data security in dual interface solutions.

The thickness of NXT-DSB provides the best solution for long life-span products required in applications such as banking, transportation, leisure and entertainment.

Key Features

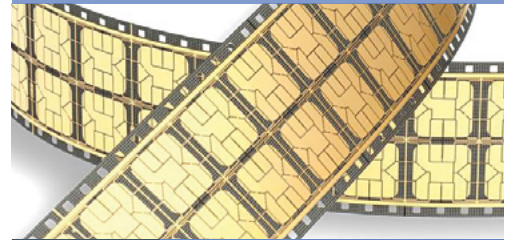
- Very high corrosion resistance
- Worldwide reference plating family
- Suitable for external exposure
- Dual interface solution

Typical Product Designs

Part Number	Modules	Cavity	Chip Dimension
9X36008	8	No	4.1 x 3.9 mm
9X33217	8	No	4.1 x 6.4 mm



MICROCONNECTORS



Overview

Material

- Film base: Copper-clad Epoxy glass
- Adhesive: High temperature modified Epoxy MCHT
- Copper: ED29 μ

Thickness

- Total: 203 \pm 20 μ m / 209 \pm 20 μ m
- Plating Thickness
 - Contact side:
 - Ni: 2.0 (-0.6 +1.0) μ m
 - Au: 0.10 \pm 0.05 μ m
 - Back side:
 - Ni: 5.0 (-2.0 +5.0) μ m
 - Au: 0.3 (-0.1 +0.6) μ m

Temperature Resistance

- 3 minutes at 260°C
- 21 hours at 160°C

Plating Performance

Corrosion resistance: Very high
Chemical resistance: Very high

Compliance Labels

- ISO 10373
- ISO 7810

Application Area

- Financial services
- Leisure and entertainment
- Transportation

Options

- Gold / Palladium
- Micro-etched / Fully-etched
- Colored tape: Red, blue, orange